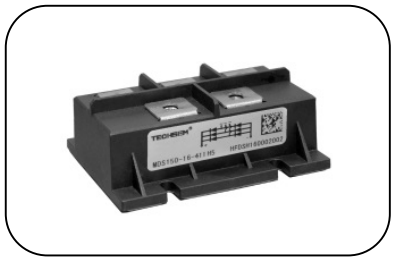


Features：

- **n** Isolated mounting base 2500V~
- **n** Solder joint technology with Increased power cycling capability
- **n** Space and weight saving

Typical Applications

- **n** Inverter
- **n** Inductive heating
- **n** Chopper

V_{RSM}	V_{RRM}	Type & Outline
900V	800V	MDS150-08-411H5
1100V	1000V	MDS150-10-411H5
1300V	1200V	MDS150-12-411H5
1500V	1400V	MDS150-14-411H5
1700V	1600V	MDS150-16-411H5
1900V	1800V	MDS150-18-411H5

SYMBOL	CHARACTERISTIC	TEST CONDITIONS	T_j(°C)	VALUE			UNIT
				Min	Type	Max	
I_O	DC output current	Three-phase full wave rectifying circuit, T_C=100°C	150			150	A
I_{RRM}	Repetitive peak current	at V_{RRM}	150			12	mA
I_{FSM}	Surge forward current	10ms half sine wave V_R=0	150			1.3	kA
I^2t	I^2t for fusing coordination					8.45	A^2s*10^3
V_{FO}	Threshold voltage		150			0.75	V
r_F	Forward slope resistance					2.4	mW
V_{FM}	Peak forward voltage	I_{FM}=150A	25			1.40	V
$R_{th(j-c)}$	Thermal resistance Junction to case	Single side cooled, per total				0.14	°C /W
$R_{th(c-h)}$	Thermal resistance case to heatsink	Single side cooled, per total				0.07	°C /W
V_{iso}	Isolation voltage	50Hz,R.M.S,t=1min,I_{iso}:1mA(max)		2500			V
F_m	Terminal connection torque(M6)			4.5		6.0	N·m
	Mounting torque(M5)			2.5		4.0	N·m
T_{vj}	Junction temperature			-40		150	°C
T_{stg}	Stored temperature			-40		125	°C
W_t	Weight				330		g
Outline	411H5						

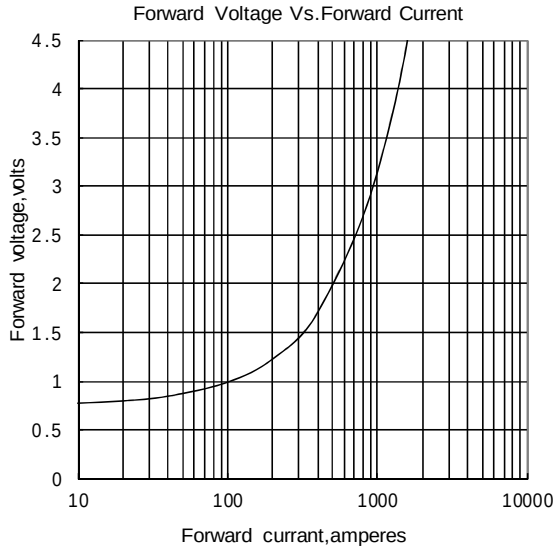


Fig.1

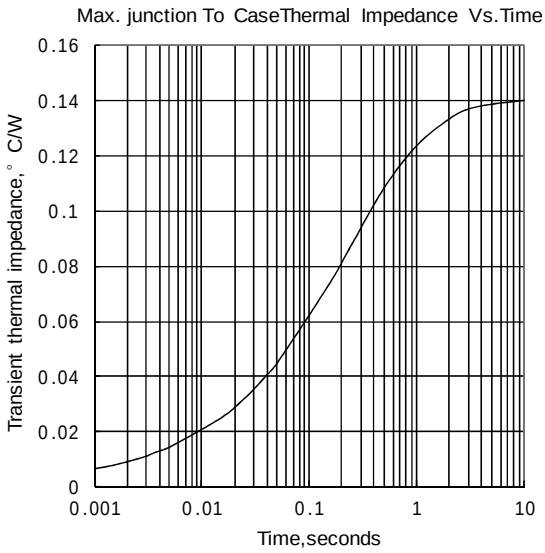


Fig.2

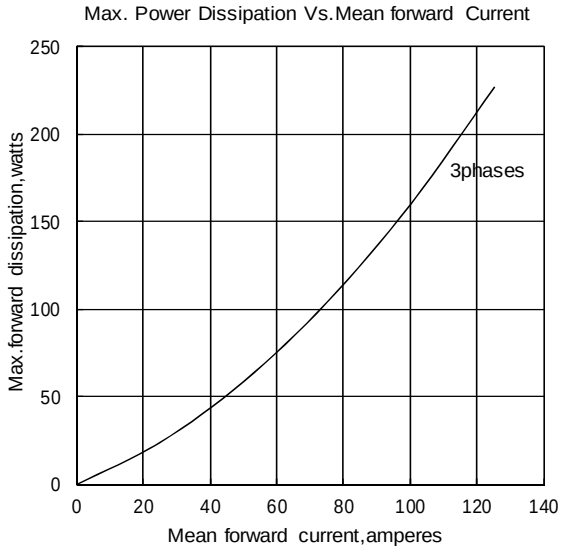


Fig.3

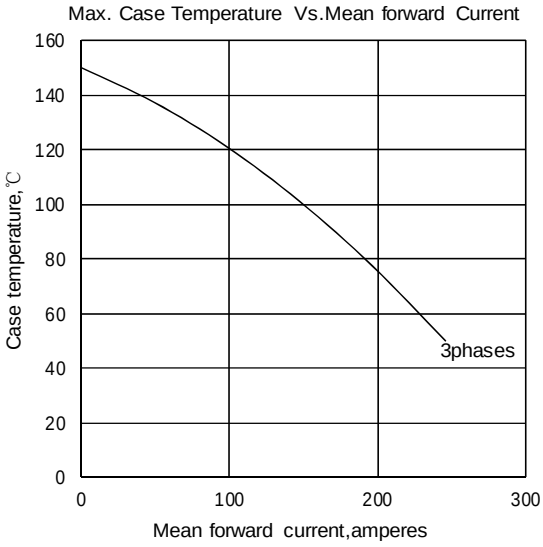


Fig.4

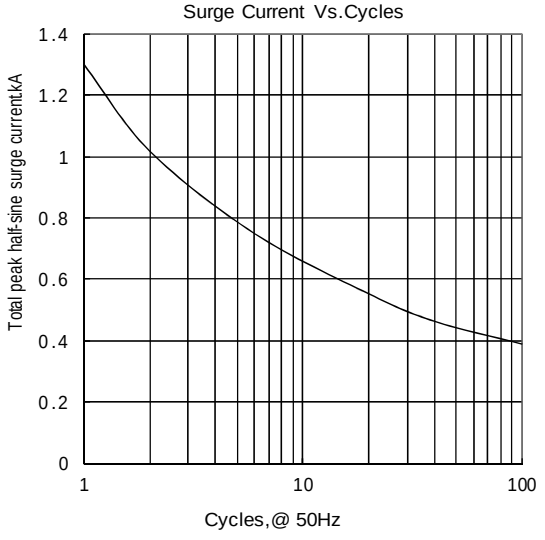


Fig.5

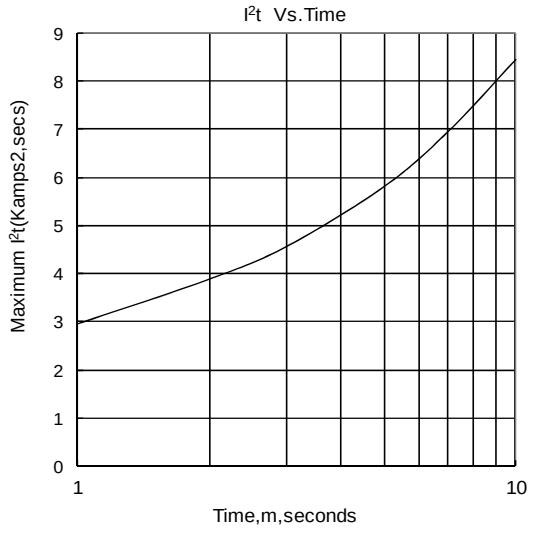
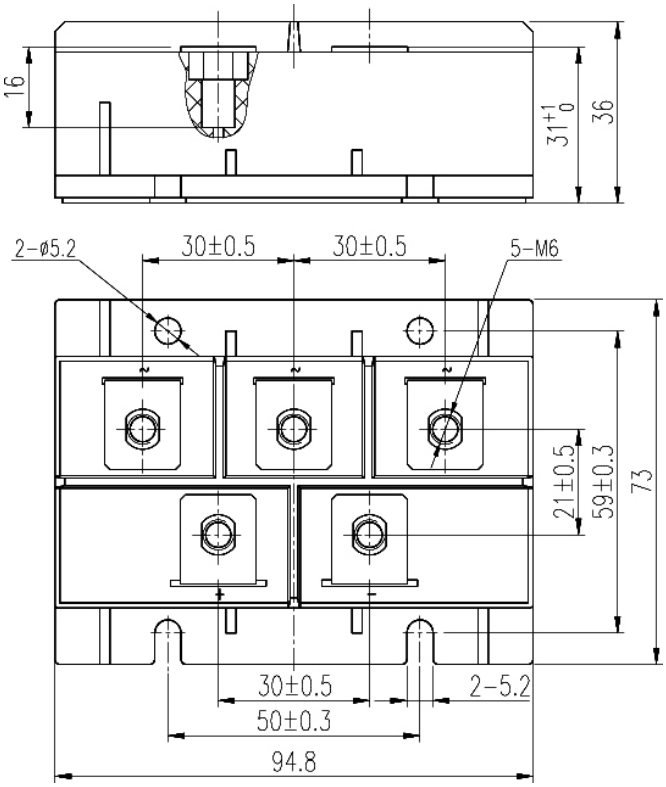
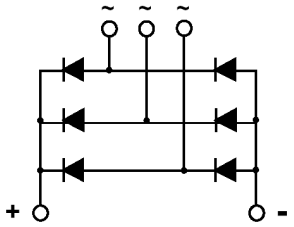


Fig.6

Outline:





Unmarked dimensional tolerance：±0.5mm

TECHSEM reserves the right to change specifications without notice.